



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





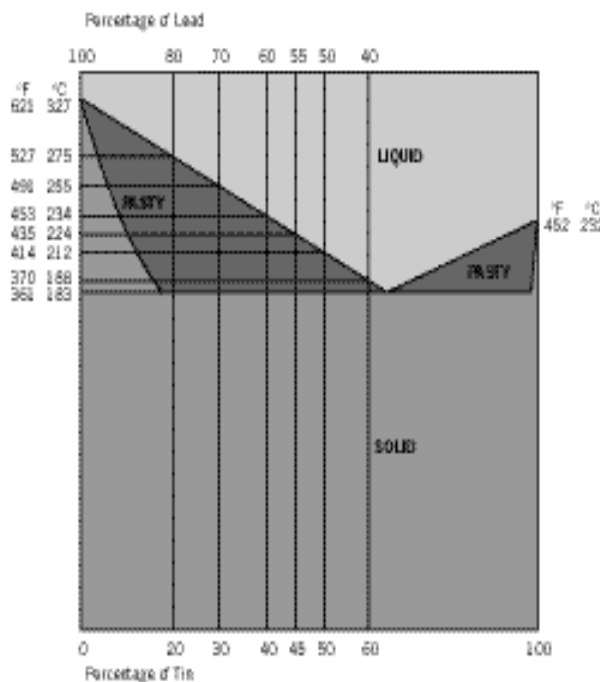
# PROPERTIES OF SOLDERS

This data sheet lists the most popular solders supplied as solid or flux-cored wire, bar, stick or cream. We are always pleased to receive enquiries for alternative specifications.

## TIN/LEAD ALLOYS

From the following diagram, it can be seen that most tin/lead solders have a plastic range, i.e. on heating they are pasty between the solid and liquid states. The solders are solid at 183°C (361°F).

According to the alloy composition they have different plastic ranges. 60/40 tin/lead alloy for example becomes liquid at 188°C (370°F) and therefore has a plastic range of 5°C (9°F), 40/60 tin/lead has a plastic range of 51°C (92°F).



For applications such as wave soldering of electronic assemblies, the requirement for a solder with a relatively low melting point in conjunction with a short freezing range leads to the choice of 63/37 or 60/40 Sn/Pb alloy. Although 63/37 is the eutectic alloy, 60/40 is often used in practice as the slightly higher 5°C freezing range of 60/40 is of no practical significance and 60/40 is a little cheaper than 63/37. Under conditions of slow cooling, 60/40 may give duller joints than 63/37 but this is a purely cosmetic effect.

Lowering the tin content increases the pasty range and raises the liquidus temperature whilst of course reducing the cost of the alloy. Wetting

properties tend to fall off with the reduced tin content.

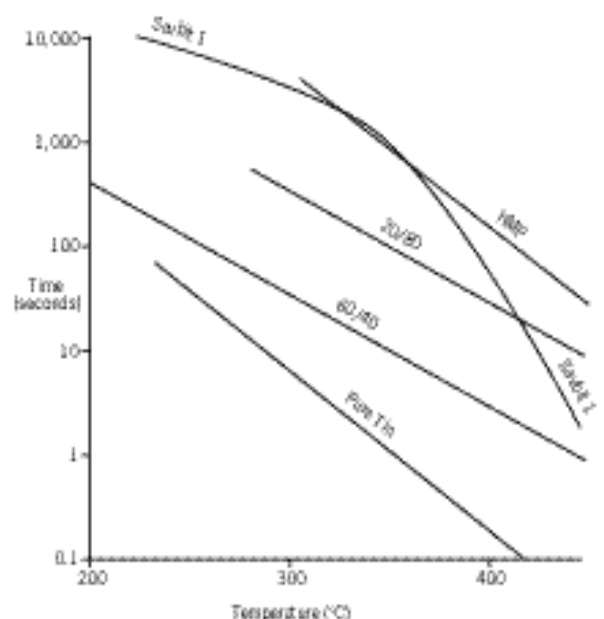
As far as obtaining a low melting point is concerned, there is no advantage in using a higher tin content than 63/37, since the higher tin content alloys have higher melting points and cost more.

## ERSIN MULTICORE SAVBIT ALLOY

- SAVES Copper and Iron-plated Soldering Iron Bits
- SAVES failure of soldered joints as Savbit prevents erosion of copper wires and copper plating
- SAVES costs and improves reliability

Ersin Multicore Savbit Solder is produced especially to overcome the problem of ordinary tin/lead solders dissolving copper. It is an alloy to which a precise amount of copper has been added so that no further copper absorption should take place during soldering.

The breakage time of 0.067mm copper wire in various solders as a function of temperature is shown below.



Savbit solder has been used by leading electronics manufacturers throughout the world for over forty years. Savbit was originally used to increase the life of copper soldering iron bits. Soldering speed and efficiency are increased by keeping the iron in good condition. Iron-plated bits having a longer life

than plain copper tips are now commonly used but they also fail eventually (usually by cracking of the plating) and then erode rapidly unless Savbit solder is used.

It has also been proved that the use of Savbit alloy can improve the strength and reliability of soldered joints very considerably. This is because ordinary tin/lead alloys can erode thin copper wires (as used for leads of electronic components) and thin copper films (as used on printed circuit boards.) This erosion is between 50 and 100 times slower at normal soldering temperatures when Savbit alloy is used.

Savbit solder with Ersin 362 flux has special M.O.D. approval DTD 900/4535. At high soldering temperatures (above 350°C) Multicore HMP alloy gives the best strength.

## HMP SOLDER

The presence of 1.5% silver substantially improves strength and wetting power compared to 5/95 Sn/Pb solder.

### Applications

**Making nearby soldered joints:** A useful application of a high melting point alloy is the soldering of joints close to each other in such a way that the first joint is not re-melted while the later joint, or joints, are being made. The first joint is made with HMP alloy (296-301°C) and the further joints are made with successively lower melting point alloys, for example - 60/40 tin/lead alloy (183-188°C) and good control of soldering temperatures.

**Service at high temperatures:** The maximum safe service temperature for any solder alloy subjected to stress is about 40°C below the solidus melting temperature, HMP alloy can therefore be relied upon in service up to about 255°C compared with about 145°C for the common tin/lead alloys. HMP alloy is consequently particularly suitable for soldering electric motors, car radiators, high temperature lamps and other products which are likely to meet relatively high temperatures during their working life.

If HMP is used to solder tin/lead coated components, the resulting soldered joint will be a new alloy with a lower melting point than HMP alloy. This will depend on the thickness and composition of the coating. The coating itself could therefore be HMP alloy if necessary.

**Service at very low temperatures:** Tin/Lead alloys containing more than 20% of tin become brittle at temperatures below about -70°C. The HMP alloy containing 5% of tin remains ductile (non-brittle) down to below -200°C. Multicore HMP alloy is also recommended therefore for service in extremely cold conditions.

**Creep strength of HMP alloy:** From information supplied, it is clear that an outstanding feature is its very great improvement in resistance to creep by comparison with the tin/lead solders, both at normal and at elevated temperatures. At 150°C for example, a 50/50 tin/lead solder will fail under a load of 0.7 N mm<sup>-2</sup> in approximately 10 hours. The following results were obtained with HMP alloy at the same temperature.

Load (N mm <sup>-2</sup> )	Time to failure
3.4	150 hours
1.7	about 1 year
0.7	no creep

## 96S TIN/SILVER SOLDER

Multicore 96S alloy is the pure tin/silver eutectic alloy; like pure tin, it is bright, hardly tarnishes, is lead-free and non-toxic, but unlike pure tin it is relatively strong.

It has higher electrical conductivity than other soft solders and a melting point approximately 40°C higher than either 60/40, 63/37 or LMP alloys. For one or more of these reasons it finds uses, despite its higher cost, in the form of ERSIN Multicore Solder Wire usually in Electronics applications. The alloy itself is however used more extensively for non-electrical applications in the form of Multicore ARAX Acid-cored Solder, particularly for soldering stainless steel.

96S has better wetting power on stainless steel than other solders. Note the silver in 96S does not suppress absorption of silver from silver plated surfaces or metallisations into the solder, so 96S is not suitable for soldering to such surfaces.

## Sn62 SOLDERS

### Applications

**Soldering silver-plated surfaces:** The presence of the 2% silver in Sn62 alloys suppresses absorption of silver from silver-plated surfaces into the solder. A good joint is thus obtained. If an ordinary tin/lead alloy is used on silver-plated surfaces, the silver can be lifted from the surface and dissolved into the solder so that a good joint is unlikely. The attachment of terminations in the manufacture of silver ceramic capacitors is a typical application.

## 95A, 97Cu AND 99C SOLDERS

### Applications

**Lead-free plumbing solders:** 97Cu and 99C are lead-free (non toxic) plumbing solders with superior wetting and capillary filling characteristics.

**Lead-free high temperature solder:** 95A is a high melting point solder suitable for general purpose soldering where a lead-free alloy is require

## NOMINAL COMPOSITIONS AND SPECIFICATIONS

Alloy	Tin	Lead	Antimony	Copper	Silver	Specification
Pure Tin	100	-	-	-	-	EN 29453 and J-STD-006
63EN	63	balance	-	-	-	EN 29453 and J-STD-006
60EN	60	balance	-	-	-	EN 29453 and J-STD-006
50EN	50	balance	-	-	-	EN 29453 and J-STD-006
45EN	45	balance	-	-	-	EN 29453 and J-STD-006
40EN	40	balance	-	-	-	EN 29453 and J-STD-006
35EN	35	balance	-	-	-	EN 29453 and J-STD-006
30EN	30	balance	-	-	-	EN 29453 and J-STD-006
20/80	20	balance	-	-	-	BS219
15/85	15	balance	-	-	-	BS219
Sn63	63	balance	-	-	-	EN 29453 and J-STD-006
Sn60	60	balance	-	-	-	EN 29453 and J-STD-006
Sn50	50	balance	-	-	-	EN 29453 and J-STD-006
Sn40	40	balance	-	-	-	EN 29453 and J-STD-006
95A	95	balance	-	-	-	EN 29453 and J-STD-006
97Cu	97	balance	-	-	-	EN 29453
99C	99.3	balance	-	-	-	EN 29453
Sav1	50	balance	-	-	-	EN 29453
HMP	5	balance	-	-	-	EN 29453
Sn62	62	balance	-	-	-	EN 29453 and J-STD-006
96S	96.3	balance	-	-	-	EN 29453 and J-STD-006

## TENSILE STRENGTHS, DENSITY AND ELECTRICAL CONDUCTIVITY

Ersin Multicore Solder	Ultimate Tensile Strength		Density (g cc-1)	Electrical conductivity (% IACS)
	(N mm-2)	(tons in-2)		
			11.1	
HMP	36	2.3	7.2	8.0
95A	31	2.0	7.3	10.8
Pure Tin	12	0.8	10.2	13.9
15/85	49	3.2	7.5	8.5
96S	54	3.5	10.0	13.9
20/80	51	3.3	9.7	8.7
30EN	49	3.2	9.3	9.3
40EN	47	3.1	9.1	10.1
45EN	47	3.1	8.9	10.5
Sav1	55	3.5	8.9	10.9
Sn50	45	2.9	8.9	10.9
50EN	47	3.1	8.5	10.9
Sn60	48	3.1	8.5	11.5
60EN	48	3.1	8.4	11.5
Sn63	67	4.3	8.5	11.9
Sn62	90	5.9		11.5

The UTS listed above refers to the bulk solder. The values give a guide to the relative strengths at room temperature of identical joints made with different solder alloys, but should not be used to calculate absolute joint strengths, which depend primarily on the conditions of test; thanks are due to the International Tin Research Institute for their co-operation in arriving at values all determined under the same conditions, viz specimens freshly cast at 50°C above liquidus, unmachined, tested at 20°C at 1/16in. per minute strain rate. 1N mm-2 = 145 psi = 0.102 kg mm-2 = 0.065 tons in-2.

## COLOUR CODES FOR WIRE, TEMPERATURES AND USES

Alloy	Multicore	Melting	Recommended	Uses	
		Solidus (°C)	Liquidus (°C)		
Sn63	Black on white	183	183	243	High quality work requiring low melting point alloy.
60EN	Red on white	183	188	248	
Sav1	Green on white	183	215	275	Hand soldering radio, telephone and electrical equipment; batteries.
50EN	Black on white	183	212	272	
45EN	Black on white	183	224	284	
40EN	Green on white	183	234	294	
30EN	Black on white	183	255	315	Fuses, motors, radiators and lamps.
20/80	Purple on white	183	275	335	Lamps.
15/85	Orange on white	227	288	348	Lamps.
Sn62	Red on blue	179	179	239	Particularly useful when soldering ceramics or other silver-coated surfaces.
Pure Tin	Red on green	232	232	292	Used when a lead-free solder is required.
HMP	Blue on white	296	301	361	Special High Melting Point solder.
95A	Black on white	236	243	303	High melting lead-free alloy.
96S	Black on white	221	221	281	Bright, strong, non-toxic lead-free solder



[www.multicore.com](http://www.multicore.com)

## MULTICORE SOLDERS

These data are based on information believed to be reliable and are offered in good faith, but MULTICORE MAKES NO WARRANTIES EITHER EXPRESS OR IMPLIED AS TO THEIR ACCURACY AND ASSUMES NO LIABILITIES ARISING OUT OF THEIR USE BY OTHERS as conditions and methods of use of the products are beyond MULTICORE'S control. The prospective user should determine the suitability of the product before using it on a commercial scale. MULTICORE warrants only that the product will conform to its physical descriptions. MULTICORE MAKES NO OTHER WARRANTIES EXPRESS OR IMPLIED AND EXPRESSLY DISCLAIMS ANY IMPLIED WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE. IN NO EVENT SHALL MULTICORE BE RESPONSIBLE FOR SPECIAL, INCIDENTAL OR CONSEQUENTIAL DAMAGES, WHETHER THE CLAIM IS IN CONTRACT, NEGLIGENCE OR OTHERWISE.